

ABSTRACT OF THE DISCLOSURE

FLAME-RETARDANT RESIN COMPOSITION
AND SEMICONDUCTOR SEALANT USING THE SAME

The present invention provides a flame-retardant resin composition comprising:

(A) an epoxy resin other than halogenated epoxy resins, having at least two epoxy groups in the molecule,

(B) a curing agent, and

(C) a product obtained by reacting (C1) a phosphorus compound having at least one P-H linkage in the molecule, with (C2) a compound having, in the molecule, at least one functional group selected from the group consisting of C-C double bond, epoxy group, alcoholic hydroxyl group and carbonyl group, and at least one functional group selected from the group consisting of epoxy group, phenolic hydroxyl group, amino group, cyanate ester group and isocyanate group, and having a phosphorus content of 0.3% by weight to 8% by weight. This resin composition has high flame retardancy without using any halogen compound and does not impair the properties of an article to which the composition is applied.